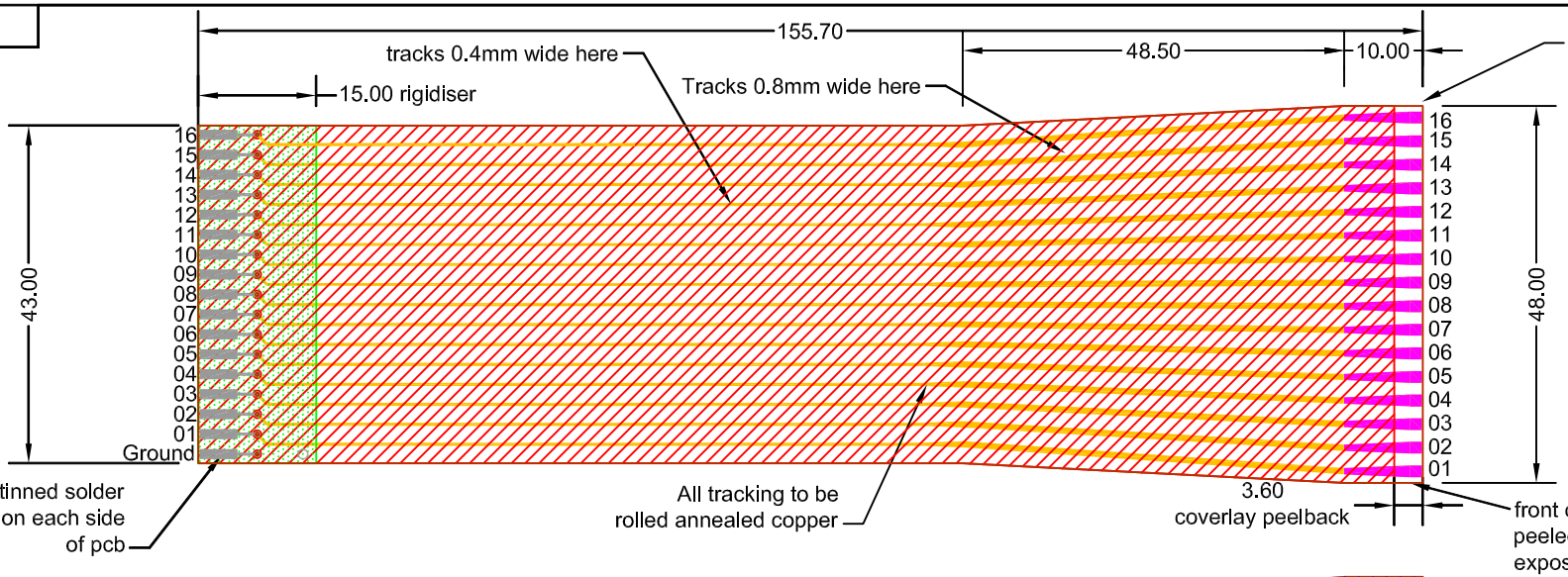
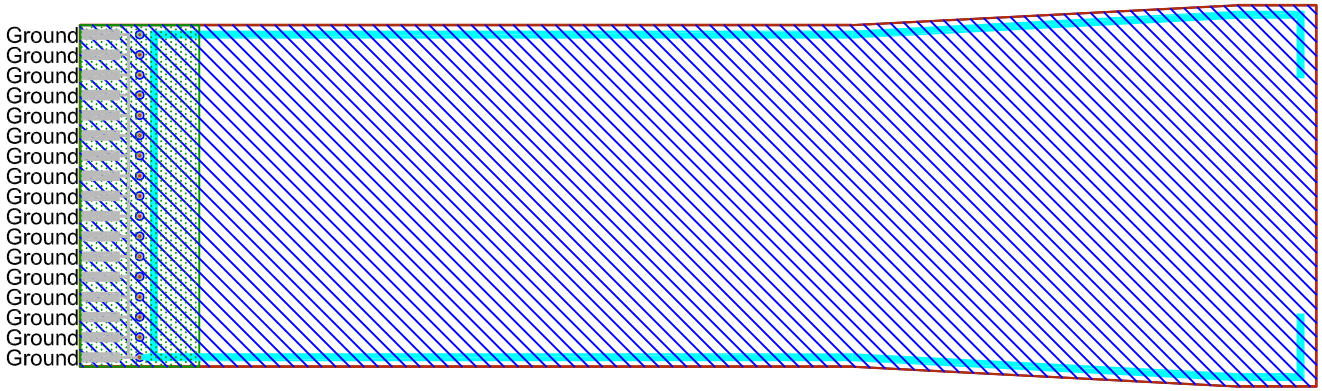
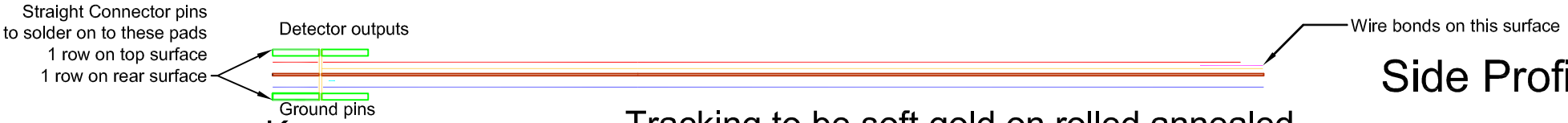
Drg. No. C-2127



Front View



Rear Viewed Through Front



Side Profile

Key

- PCB Rigidiser
- Front Coverlay
- Front Tracking
- Tinned Pads
- Kapton Outline
- Rear Tracking
- Rear Coverlay
- Soft Gold Pads

Tracking to be soft gold on rolled annealed copper NO NICKEL

For Use with 3M connector 3431-2303

Drawn.	Checked.	Date	Tolerances Unless Stated	Material - 0.3mm assembled thickness flexi, with 2 x 1.0mm thick FR4 PCB material rigidisers.
N.W	S.W	20/10/2009	Package O/D ± 0.1mm	Plating - rolled annealed copper tracking, with 16 soft gold pads and 34 tinned donuts.
Design Approved.			Package Hole Ø ± 0.05mm	Coverlay Front - Yes, Peeled back to expose bond pads on front.
			Package Hole Pos'n ± 0.1mm	Coverlay Rear - Yes
customer			Material Thickness ± 0.1mm	Ledge - N/A

Title. Design W (D/S) Kapton for use with LASSA Package Rear Connections. Rev 4

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graphics@micronsemiconductor.co.uk

Scale. N/A | Dims In. mm | Drg. No. C-2127